

### **Amendments to the Claims**

This listing of claims will replace all prior versions, and listings of claims in the application:

#### **Listing of Claims:**

Claims 1-33 (Canceled)

Claim 34 (Currently Amended): A semiconductor device comprising:

a BGA (ball grid array) type semiconductor device including a base plate and a plurality of bumps formed on a backside surface of the base plate; and

a CSP (chip size packaged) type semiconductor device mounted on an area of the backside surface of the base plate of said BGA type semiconductor device which does not have any bumps formed thereon,

said CSP type semiconductor device having a semiconductor element which has main and back surfaces, and side surfaces between the main and back surfaces, and a plurality of terminals which are formed on the main a front surface thereof and which are electrically connected to the plurality of bumps,

wherein the back surface and the entirety of the side surfaces of the semiconductor element are exposed.

Claim 35 (Previously Presented): The semiconductor device of claim 34, wherein the

plurality of terminals of said CSP type semiconductor device are electrically connected to the plurality of bumps via wiring patterns formed on the backside surface of the base plate.

Claim 36 (Previously Presented): The semiconductor device of claim 35, wherein the plurality of terminals of said CSP type semiconductor device are coupled to the wiring patterns via solder joints.

Claim 37 (Currently Amended): The semiconductor device of claim 34, wherein said CSP type semiconductor device is mounted on said BGA type semiconductor device so that ~~[[the]]~~ a front surface of said CSP type semiconductor device faces the backside surface of the base plate.

Claim 38 (Currently Amended): The semiconductor device of claim 34, wherein the backside surface of the base plate ~~said BGA type semiconductor device~~ is mounted to a printed circuit board via the plurality of bumps, and said CSP type semiconductor device as mounted on the backside surface of the base plate has a thickness less than a thickness of the plurality of bumps.

Claim 39 (Currently Amended): A semiconductor device comprising:  
a ~~BGA (ball grid array)~~ type first semiconductor device including

a first semiconductor element having main and back surfaces, and side surfaces between the main and back surfaces ~~mounted on a first surface of a base plate, the base plate having a second surface opposite to the first surface,~~  
and  
~~ball solder bumps on the second surface of the base plate~~ located above the back surface of the first semiconductor element, the solder ball bumps being electrically connected ~~through the base plate~~ to the first semiconductor element, the back ~~second~~ surface having an area without solder ball bumps; and  
a ~~CSP (chip size packaged)~~ type second semiconductor device mounted ~~[[on]]~~  
so as to oppose the second back surface of the base plate first semiconductor element,  
the second said CSP type semiconductor device including  
a second semiconductor element having a main surface,  
a plurality of terminals on the main surface of the second semiconductor element, and  
a resin covering the main surface of the second semiconductor element and side surfaces of the plurality of terminals, so that a back surface of the second semiconductor element is exposed from the resin,  
wherein the back and side surfaces of the first semiconductor element are exposed.

Claim 40 (Currently Amended): The semiconductor device of claim 39, wherein the

plurality of terminals of the second ~~said CSP type~~ semiconductor device are electrically connected to the ~~solder~~ ball bumps via wiring patterns formed on the back ~~second~~ surface of the first semiconductor element ~~base plate~~.

Claim 41 (Currently Amended): The semiconductor device of claim 40, wherein the plurality of terminals of the second ~~said CSP type~~ semiconductor device are coupled to the wiring patterns via solder joints.

Claim 42 (Currently Amended): The semiconductor device of claim 39, wherein the second ~~said CSP type~~ semiconductor device is mounted on the ~~second~~ back surface of ~~said base plate~~ the first semiconductor element so that the main surface of the second semiconductor element faces the back ~~second~~ surface of the ~~base plate~~ first semiconductor element.

Claim 43 (Currently Amended): The semiconductor device of claim 39, wherein the ~~second~~ back surface of the first semiconductor element ~~base plate~~ is mounted to a printed circuit board via the ball ~~solder~~ bumps, and the second semiconductor element as mounted on the back ~~second~~ surface of the first semiconductor element ~~base plate~~ has a thickness less than a thickness of the ~~solder~~ ball bumps.

Claim 44 (Currently Amended): The semiconductor device of claim 39, wherein a

thickness of said ~~CSP type~~ the second semiconductor device is less than a thickness of the solder ball bumps.

Claim 45 (New): The semiconductor device according to claim 34, wherein said CSP type semiconductor device has a resin that covers the main surface of the semiconductor element and side surfaces of the terminals.

Claim 46 (New): The semiconductor device according to claim 34, wherein the main surface of the semiconductor element faces the backside surface of the base plate.

Claim 47 (New): The semiconductor device according to claim 45, wherein the main surface of the semiconductor element faces the backside surface of the base plate.

Claim 48 (New): The semiconductor device according to claim 39, wherein the first semiconductor device has a plurality of conductive material, parts of the conductive material are electrically connected to the ball bumps and other parts of the conductive material are used to electrically connect to the terminals of the second semiconductor device.

Claim 49 (New): A semiconductor device comprising:

a first semiconductor device including

a first semiconductor element having main and back surfaces, and side surfaces between the main and back surfaces, and

ball bumps located above the back surface of the first semiconductor element, the ball bumps being electrically connected to the first semiconductor element, the back surface having an area without ball bumps; and

a second semiconductor device mounted so as to oppose the back surface of the first semiconductor element, the second semiconductor device including

a second semiconductor element having a main surface,

a plurality of terminals on the main surface of the second semiconductor element, and

a resin covering the main surface of the second semiconductor element and side surfaces of the plurality of terminals, so that a back surface of the second semiconductor element is exposed from the resin,

wherein the first semiconductor device has a plurality of conductive material, parts of the conductive material are electrically connected to the ball bumps and other parts of the conductive material are electrically connected to the terminals of the second semiconductor device.

Claim 50 (New): The semiconductor device according to claim 49, wherein the side surfaces of the first semiconductor element are exposed.

Claim 51 (New): The semiconductor device according to claim 49, wherein the other parts of the conductive material are located between the back surface of the first semiconductor element and the main surface of the second semiconductor element.

Claim 52 (New): The semiconductor device according to claim 50, wherein the other parts of the conductive material are located between the back surface of the first semiconductor element and the main surface of the second semiconductor element.